## SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS239F - MARCH 1993 - REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 25-Ω
  Series Resistors, So No External Resistors
  Are Required
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## description/ordering information

The 'ABT162245 devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or

from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses effectively are isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.

These devices are fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

# SN74ABT162245 . . . DGG OR DL PACKAGE (TOP VIEW)

SN54ABT162245 . . . WD PACKAGE

_			L
1DIR	]1 ~	48	1 <u>0E</u>
1B1	2	47	1A1
1B2	3	46	1A2
GND [	4	45	GND
1B3 l	5	44	1A3
1B4	6	43	1A4
V <sub>CC</sub>		42	□ v <sub>cc</sub>
1B5		41	1A5
1B6	9	40	1A6
GND [	10	39	GND
1B7 [	11	38	1A7
1B8	12	37	1A8
2B1 [	13	36	2A1
2B2 [	14	35	2A2
GND[	15	34	GND
2B3 [	16	33	2A3
2B4 [	17	32	2A4
v <sub>cc</sub> [	18	31	□ v <sub>cc</sub>
2B5	19	30	2A5
2B6 [	20	29	2A6
GND[	21	28	GND
2B7 [	22	27	2A7
2B8 [	23	26	] 2A8
2DIR [	24	25	20E

#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	CCOD DI	Tube	SN74ABT162245DL	ADT460045		
-40°C to 85°C	SSOP – DL	Tape and reel	SN74ABT162245DLR	ABT162245		
	TSSOP - DGG	Tape and reel	SN74ABT162245DGGR	ABT162245		
-55°C to 125°C	CFP – WD	Tube	SNJ54ABT162245WD	SNJ54ABT162245WD		

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.



SCBS239F - MARCH 1993 - REVISED JUNE 2004

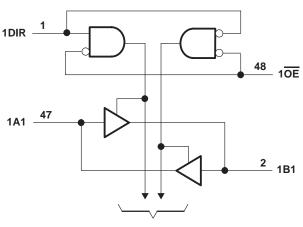
## description/ordering information (continued)

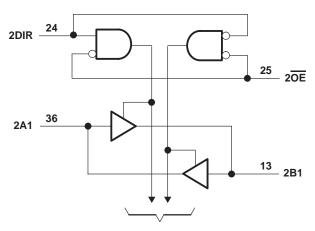
To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{\text{CC}}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### **FUNCTION TABLE** (each 8-bit section)

INP	UTS			
OE	DIR	OPERATION		
L	L B data to A bus			
L	Н	A data to B bus		
Н	Χ	Isolation		

## logic diagram (positive logic)





**To Seven Other Channels** To Seven Other Channels

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT162245 (B port)	96 mA
SN74ABT162245 (B port)	
SN54/74ABT162245 (A port)	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	
DL package	
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



# SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS239F - MARCH 1993 - REVISED JUNE 2004

# recommended operating conditions (see Note 3)

			SN54ABT	162245	SN74ABT	162245	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ <sub>I</sub>	Input voltage		0	Vcc	0	Vcc	V
	I Park Town Landowski summer	B port		-24		-32	4
ЮН	High-level output current	A port		-3		-12	mA
	Lave lavel authors avenues	B port		48		64	A
lOL	Low-level output current	A port		12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# SN54ABT162245, SN74ABT162245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCBS239F - MARCH 1993 - REVISED JUNE 2004

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54ABT	162245	SN74ABT	162245		
PAR	AMETER	TEST CON	IDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		V <sub>CC</sub> = 5 V,	$I_{OH} = -1 \text{ mA}$	3.8			2.5		2.5			
	A		$I_{OH} = -1 \text{ mA}$	3.3			3		3			
	A port	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1			
			I <sub>OH</sub> = -12 mA	2.6*					2.6		V	
VOH		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
	D nort		$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
	B port	$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -24 \text{ mA}$				2					
			$I_{OH} = -32 \text{ mA}$	2*					2			
	A port		I <sub>OL</sub> = 12 mA			8.0		0.8		8.0		
VOL	B port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.45		0.45		0.45	V	
	Броп		I <sub>OL</sub> = 64 mA			0.55*				0.55		
V <sub>hys</sub>	-				100						mV	
l <sub>i</sub>	Control inputs	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V			±1		±1		±1	μА		
	A or B ports					±20		±20		±20		
IOZH§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			10		10		10 μΑ		
I <sub>OZL</sub> §		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-10		-10		-10	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ	
. «	A port	V 55V		-25	-50	-100‡	-25	-90	-25	-100		
IO¶	B port	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0$ ,	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
	Doto inputo	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1		2		2		
∆lcc#	Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		1		0.05	mA	
	Control inputs	V <sub>CC</sub> = 5.5 V, One ir Other inputs at V <sub>CC</sub>			1.5		1.5		1.5			
Ci		V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
Cio		$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			6						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



 $<sup>^\</sup>dagger$  All typical values are at VCC = 5 V.  $^\ddagger$  This limit applies only to the SN74ABT162245.

<sup>§</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

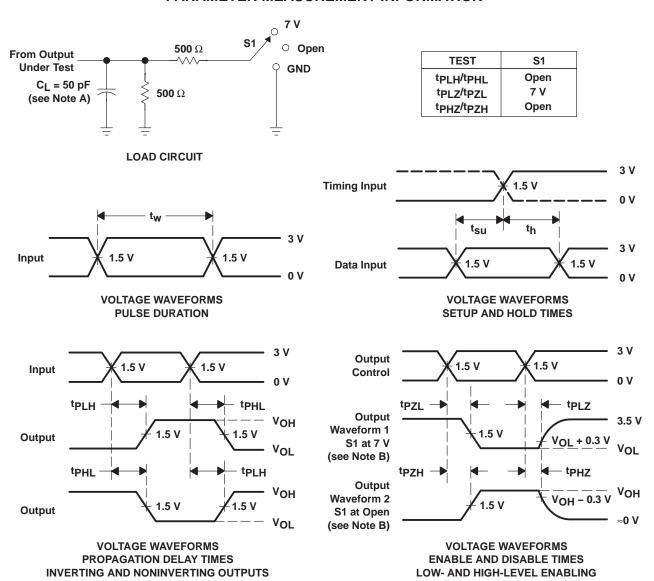
<sup>#</sup> This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

# SN54ABT162245, SN74ABT162245 **16-BIT BUŚ TRANSCEIVERS** WITH 3-STATE OUTPUTS SCBS239F - MARCH 1993 - REVISED JUNE 2004

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V A = 25°C	<u>',</u> ;	SN54ABT	162245	SN74ABT	UNIT	
	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH		Б	1	2.2	3.4	1	4.1	1	3.9	
<sup>t</sup> PHL	А	В	1	2.3	3.7	1	4.4	1	4.2	ns
<sup>t</sup> PLH			1	2.7	4.1	1	4.9	1	4.6	
<sup>t</sup> PHL	В	Α	1.5	3.1	4.6	1.5	5.2	1.5	5.1	ns
<sup>t</sup> PZH	<u>OE</u>	В	1	3.6	5.2	1	6.4	1	6.3	ns
t <sub>PZL</sub>	OE		1	3.7	5.4	1	6.5	1	6.4	
<sup>t</sup> PHZ	ŌĒ	В	2	4.4	5.8	2	6.4	2	6.3	20
t <sub>PLZ</sub>	OE .	Ь	1.5	3.3	4.7	1.5	5.6	1.5	5.2	ns
<sup>t</sup> PZH			1.5	4.1	6	1.5	7.2	1.5	7.1	
t <sub>PZL</sub>	ŌĒ	A	1.5	4.3	6.1	1.5	7.3	1.5	7	ns
<sup>t</sup> PHZ	ŌĒ	Δ.	2	4.5	6.1	2	6.8	2	6.6	ns
tPLZ	) UE	Α	1.5	3.7	5.1	1.5	6.1	1.5	5.7	

## PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq 2.5 \,$ ns,  $t_f \leq 2.5 \,$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







25-Oct-2016

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
5962-9677401QXA	ACTIVE	CFP	WD	48	1	TBD	(6) A42	(3) N / A for Pkg Type	-55 to 125	(4/5) 5962-9677401QX A SNJ54ABT162245 WD	Samples
74ABT162245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SN74ABT162245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162245	Samples
SNJ54ABT162245WD	ACTIVE	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9677401QX A SNJ54ABT162245 WD	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures. TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.





25-Oct-2016

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54ABT162245. SN74ABT162245:

Catalog: SN74ABT162245

Military: SN54ABT162245

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

www.ti.com 11-Mar-2017

## TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT162245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 11-Mar-2017



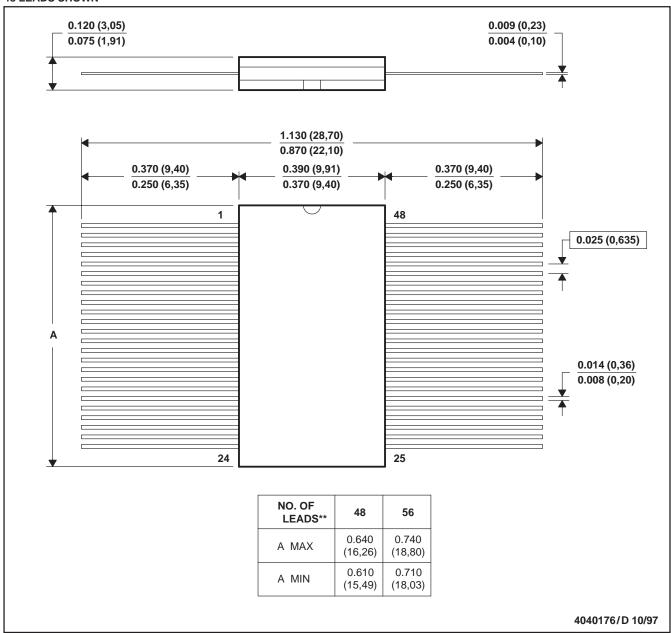
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT162245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABT162245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

## WD (R-GDFP-F\*\*)

### **CERAMIC DUAL FLATPACK**

## **48 LEADS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<a href="www.ti.com/legal/termsofsale.html">www.ti.com/legal/termsofsale.html</a>) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2019, Texas Instruments Incorporated